

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-9. (Canceled)

10. (Currently Amended) ~~A Microcomponent~~ microcomponent comprising
comprising:

_____ a hermetically-sealed microcavity delineated by a cover comprising a first layer, in which at least one hole is formed, and a second layer making the microcavity hermetic,

_____ ~~microcomponent comprising~~ a third layer arranged between the first layer and the second layer,

_____ an additional microcavity, communicating with the at least one hole and being arranged between the first layer and the third layer, and at least one additional hole, adjacent to the additional microcavity, formed in the third layer, the additional hole being offset with respect to the at least one hole and being sealed by the second layer, ~~microcomponent~~
~~comprising~~

_____ at least one mechanically tensile-stressed layer arranged above the first layer, the at least one mechanically tensile-stressed layer being different from the first layer and the second layer and, said the at least one mechanically tensile-stressed layer being capable of flexing in the a direction of the first layer and thereby reducing a space to be sealed by the second layer.

11. (Currently Amended) ~~Microcomponent~~ The microcomponent according to claim 10, wherein the additional microcavity communicates with the additional hole.

12. (Currently Amended) The microcomponent ~~Microcomponent~~ according to claim 10, wherein the hole is arranged on the highest part of the microcavity.

13. (Currently Amended) ~~The microcomponent~~Microcomponent according to claim 10, wherein the offset between the hole and the additional hole is such that the additional hole does not cover the hole, even partially.

14. (Currently Amended) ~~The microcomponent~~Microcomponent according to claim 10, wherein two additional holes are associated with each hole so that a suspended bridge, formed in the third layer and delineated by the two additional holes, covers the hole.

15. (Currently Amended) ~~Method~~A method for production of a hermetically-sealed microcavity of a microcomponent ~~according to claim 10, successively comprising the~~method comprising:

[[-]]—deposition of a sacrificial layer on a substrate,

[[-]]—deposition of a first layer forming a cover, on the substrate and sacrificial layer,

[[-]]—etching, in the first layer, of at least one hole ~~opening that opens out~~onto the sacrificial layer,

[[-]]—removal of the sacrificial layer, via the hole, so as to create a microcavity,

[[-]]—deposition of a second layer, so as to make the microcavity hermetic, ~~method comprising,~~ after etching of the hole and before removal of the sacrificial layer,

[[-]]—deposition of an additional sacrificial layer covering the hole and a part of the first layer, over the periphery of the hole,

[[-]]—deposition of a third layer on the first layer and the additional sacrificial layer,

[[-]]—etching of at least one additional hole, in the third layer, the at least one additional hole being offset with respect to the at least one hole that opens out onto the sacrificial layer, and opening out onto the additional sacrificial layer,

_____ removal of the sacrificial layer and removal of the additional sacrificial layer being performed through the at least one additional hole so as to create the microcavity, and _____ deposition of the second layer being performed on the third layer so as to seal the additional hole, ~~the method comprising~~ _____ deposition of at least one mechanically tensile-stressed layer, after deposition of the first layer, the at least one mechanically tensile-stressed layer being different from the first layer and the second layer and, said the mechanically tensile-stressed layer being capable of flexing in the direction of the first layer and thereby reducing the space to be sealed by the second layer.

16. (Currently Amended) ~~Method~~ The method according to claim 15, wherein the third layer is mechanically tensile-stressed so that ~~the~~ a part of the third layer released by removal of the additional sacrificial layer flexes in the direction of the first layer.

17. (Currently Amended) ~~Method~~ The method according to claim 15, wherein the third layer ~~is formed by~~ comprises a first mechanically tensile-stressed sub-layer covered by a second mechanically compressive-stressed sub-layer, the second mechanically compressive-stressed sub-layer being removed after the first sacrificial layer and the second sacrificial layers ~~layer~~ have been removed.

18. (Currently Amended) ~~Method~~ The method according to claim 15, ~~wherein,~~ wherein after the sacrificial layers have been removed, a mechanically tensile-stressed fourth layer is deposited on the third layer, so that the third layer and fourth ~~layers~~ layer each flex in the direction of the first layer.